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This index covers all items—papers, correspondence, reviews, etc.—that appeared in this periodical during 1989, and items from previous years that were commented upon or corrected in 1989.

The *Author Index* contains the primary entry for each item, listed under the first author's name, and cross-references from all coauthors. The *Subject Index* contains several entries for each item under appropriate subject headings, and subject cross-references.

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- Thermal factors; cf. Dielectric materials/devices, thermal factors; Heating; Hybrid integrated-circuit thermal factors; Semiconductor device thermal factors; Soldering; Surface mounting; Thick-film circuit thermal factors**
- Thermal variables measurement**
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- Thick-film circuit fabrication**
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- Thick-film circuits**
thick-film coplanar probe for time-domain measurements on microwave planar lines. *Muthukrishnan, Narayanamoorthy, +, T-CHMT Jun 89 297-302*
- Thick-film resistors**
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- Thick films**
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- Thin-film circuit packaging**
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- Thin-film devices**
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- Thin films**
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- Thin films; cf. Integrated-circuit interconnections; Plastic films; Superconducting films**
- Time-domain measurements**
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- Tin materials/devices**
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- Tin materials/devices; cf. Contacts; Semiconductor device bonding; Soldering; Surface mounting**
- Transducers; cf. Moisture transducers**
- Transformers; cf. Pulse transformers**
- Transient analysis; cf. Circuit transient analysis; Pulse analysis**
- Transistors; cf. MESFETs; Microwave bipolar transistors**
- Transmission lines; cf. Strip transmission lines**

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- Vacuum interrupters**
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- Very large-scale integration**
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- Wear; cf. Mechanical factors**
- Wedges**
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- Welding**
welding of asperities between two gold films; observation by transmission electron microscopy. *Chan, Siu-Wai, T-CHMT Mar 89 39-42*
- Wiring; cf. Integrated-circuit interconnections; Printed circuits**

Y

- Yttrium materials/devices**
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- Yttrium materials/devices; cf. Superconducting...**